




## Materials Declaration Form

<b>IPC</b>	<b>1752</b>	<b>Version</b>	<b>2</b>
<b>Form Type *</b>	<b>Distribute</b>		
<b>Sectionals *</b>	<b>Material Info</b> <b>Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>
		<b>* : Required Field</b>	

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2015-07-06</b>
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>Rossana Bonaccorso</b>	<b>Representative Title</b>	<b>IPD MD Champion</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

Uncertainty Statement	
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Legal Statement	
<b>Supplier Acceptance *</b>	<b>true</b>
	<b>Legal Declaration *</b>
	<b>Standard</b>
<b>Legal Statement</b>	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	TLD2*QD0FB32	A	SHENZHEN B/E	2015-07-06
Amount	UoM	Unit type	ST ECOPACK Grade	
1435.1	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2, 9.15, 4.5	2	GULL WING	
Comment	Package: D2PAK, MD valid for CP:STB35NF10T4.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2014				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TLD2*QD0F832					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	6.506	mg	supplier	die	Silicon (Si)	7440-21-3		6.317	mg	970950	4402
				supplier	metallization	Aluminium (Al)	7429-90-5		0.089	mg	13680	62
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	154	1
				supplier	Passivation	Silicon Oxide	7631-86-9		0.044	mg	6763	31
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	461	2
				supplier	back side metallization	Gold (Au)	7440-57-5		0.009	mg	1383	6
Leadframe	Copper & its alloys	779.567	mg	supplier	alloy	Copper (Cu)	7440-50-8		777.537	mg	997396	541800
				supplier	alloy	Iron (Fe)	7439-89-6		0.358	mg	459	249
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.654	mg	839	456
				supplier	metallization	Nickel (Ni)	7440-02-0		1.012	mg	1298	705
				supplier	metallization	Phosphorus (P)	12185-10-3		0.006	mg	8	4
Soft solder	Solder	6.088	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	5.814	mg	954993	4051
				supplier	solder	Silver (Ag)	7440-22-4		0.152	mg	24967	106
				supplier	solder	Tin (Sn)	7440-31-5		0.122	mg	20039	85
Bonding wires	Other inorganic materials	1.343		supplier	wire	Aluminium (Al)	7429-90-5		1.342	mg	999255	935
				supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	745	1
Encapsulation	Other Organic Materials	639.107	mg	supplier	mold compound	Silica, vitreous	60676-86-0		559.219	mg	875001	389672
				supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-bis-oxirane	EC 413-900-7		25.564	mg	40000	17813
				supplier	mold compound	Epoxy Resin	25068-38-6		19.173	mg	30000	13360
				supplier	mold compound	phenol resin	29690-82-2		31.955	mg	49999	22267
				supplier	mold compound	Carbon black	1333-86-4		3.196	mg	5001	2227
connections coating	Solder	2.489	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1734